

L Number	Hits	Search Text	DB	Time stamp
1	235	(((silylation and heat\$3) and pin) or (((118/715,724,725,726).CCLS.) and (heat or heated or heating) and (lift adj pin)) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)) or (((118/715,724,725,726).CCLS.) and (gas adj ring)) or ((heat or heating or heated) and (lift adj pin) and (gas near ring)) or (((heat or heating or heated) and (lift adj pin) and (ring)) and (substrate or wafer))) and @pd>=20021022) or (((preheat or preheated or preheating) or (pre adj (heat or heating or heated))) and (lift adj pin) and (ring)) and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:31
2	84	(((silylation and heat\$3) and pin) or (((118/715,724,725,726).CCLS.) and (heat or heated or heating) and (lift adj pin)) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)) or (((118/715,724,725,726).CCLS.) and (gas adj ring)) or ((heat or heating or heated) and (lift adj pin) and (gas near ring)) or (((heat or heating or heated) and (lift adj pin) and (ring)) and (substrate or wafer))) and @pd>=20021022) or (((preheat or preheated or preheating) or (pre adj (heat or heating or heated))) and (lift adj pin) and (ring)) and (substrate or wafer))) and @pd>=20030321	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:35
-	4323	silylation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:41
-	2976	silylation and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:42
-	49	(silylation and heat\$3) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	9099	(118/715,724,725,726).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:54
-	156	(((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	20	(((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:11

-	126	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 10:28
-	126	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 11:57
-	20	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	156	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	27	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) not (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring) (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	4	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((purge or inert) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 10:45
-	0	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:06
-	32	((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	62	((118/715,724,725,726).CCLS.) and (gas adj ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	54	heat\$3 and (lift adj pin) and (gas near ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:08

-	44	(heat\$3 and (lift adj pin) and (gas near ring)) not (((118/715,724,725,726).CCLS.) and (gas adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:05
-	617	heat\$3 and (lift adj pin) and (ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:17
-	494	(heat\$3 and (lift adj pin) and (ring)) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:08
-	327	((heat\$3 and (lift adj pin) and (ring)) and (substrate or wafer)) not (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring) (heat\$3 and (lift adj pin) and (gas near ring)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:19
-	219	lund-j\$.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 15:29
-	207	lund-j\$.xp.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 15:29
-	28	("3830194" "4125391" "4493977" "4503807" "4533820" "4817558" "4828224" "4836138" "4854263" "4920918" "4958061" "4993358" "5000113" "5085887" "5113929" "5148714" "5156820" "5179677" "5198034" "5215588" "5269847" "5305417" "5414244" "5444815" "5445675" "5446825" "5487127" "5970213").PN.	USPAT	2002/10/23 15:43
-	57	4817558.URPN.	USPAT	2002/10/23 15:44
-	144	(lund-j\$.xa. or lund-j\$.xp.) and (electrode or showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/30 13:52
-	60	(silylation and heat\$3) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	178	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:05

-	0	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:06
-	34	((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	67	((118/715,724,725,726).CCLS.) and (gas adj ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	74	heat\$3 and (lift adj pin) and (gas near ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:09
-	584	(heat\$3 and (lift adj pin) and (ring)) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:42
-	112	(((silylation and heat\$3) and pin) or (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)) or (((118/715,724,725,726).CCLS.) and (gas adj ring)) or (heat\$3 and (lift adj pin) and (gas near ring)) or (heat\$3 and (lift adj pin) and (ring)) and (substrate or wafer))) and @pd>=20021022	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:18
-	49	((preheat\$3 or (pre adj heat\$3)) and (lift adj pin) and (ring)) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:19
-	151	(((silylation and heat\$3) and pin) or (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)) or (((118/715,724,725,726).CCLS.) and (gas adj ring)) or (heat\$3 and (lift adj pin) and (gas near ring)) or (heat\$3 and (lift adj pin) and (ring)) and (substrate or wafer))) and @pd>=20021022 or (((preheat\$3 or (pre adj heat\$3)) and (lift adj pin) and (ring)) and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:25
-	3	("6402401").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:44

-	0	("6402401").PN.) and pin and silation and (preheat\$3 or (pre adj heat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:46
-	0	("6402401").PN.) and pin and (preheat\$3 or (pre adj heat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:47
-	1	("6402401").PN.) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:47